



US00D360599S

# United States Patent [19]

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Wada et al.

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[54] MEASUREMENT SCANNER FOR SEMI-CONDUCTOR

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[73] Assignee: **Hitachi, Ltd.**, Tokyo, Japan

[\*\*] Term: **14 Years**

[21] Appl. No.: **25,210**

[22] Filed: **Jul. 26, 1994**

[30] **Foreign Application Priority Data**

Apr. 15, 1994 [JP] Japan ..... 6-10335

[52] U.S. Cl. .... **D10/75**

[58] Field of Search ..... D10/46, 75; D13/123, D13/162, 163; D14/102, 107; D24/186; 348/91, 92, 93, 94, 95, 125, 130, 135, 142, 161, 162; 356/380, 386, 387, 121, 237; 360/9.1, 72.1; 382/34; 250/223 B

[56] **References Cited**

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D. 332,616 1/1993 Hashimoto et al. .... D24/186 X  
D. 352,910 11/1994 Yamamoto et al. .... D10/75

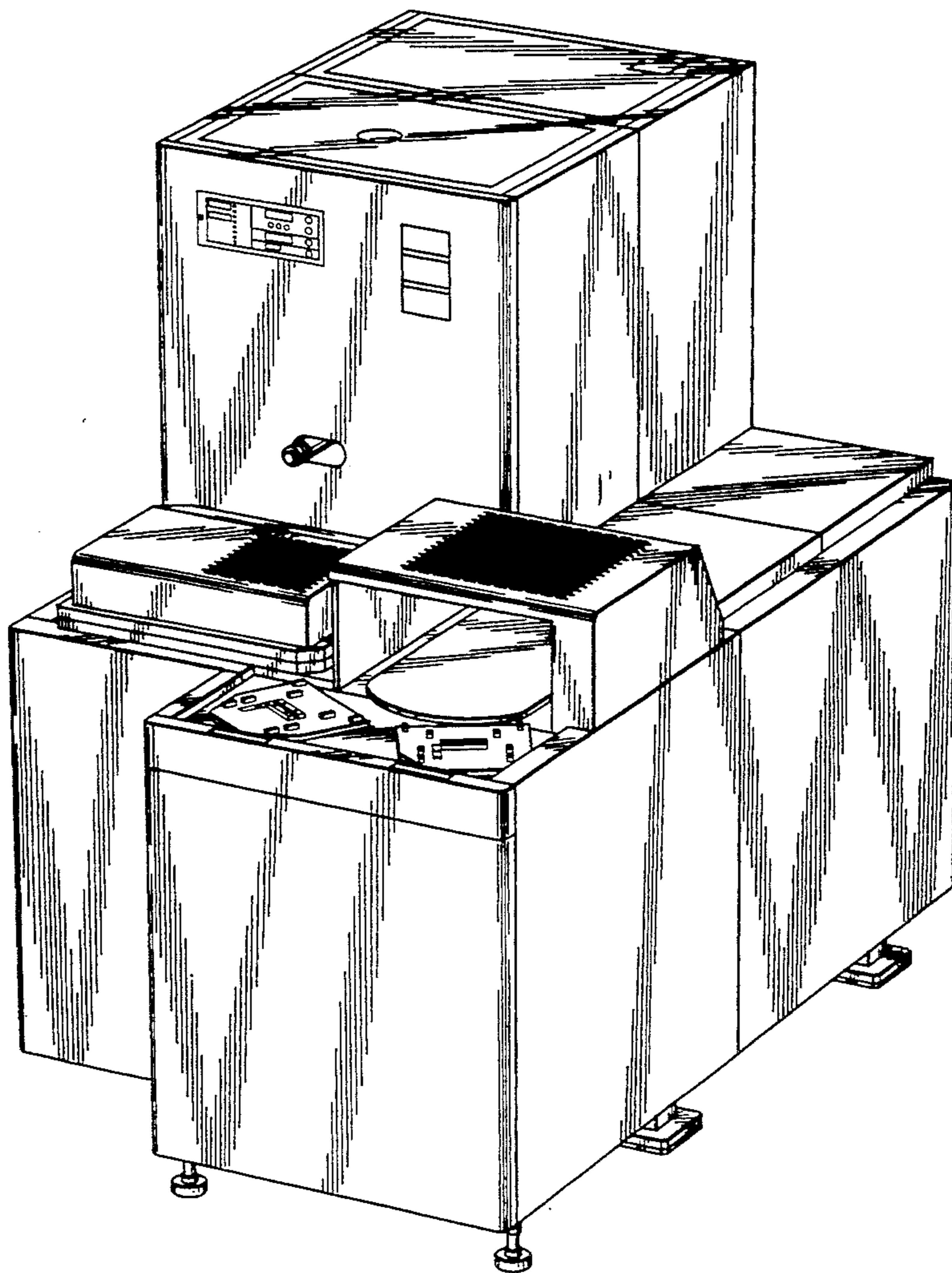
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*Attorney, Agent, or Firm*—Antonelli, Terry, Stout & Kraus

[57] **CLAIM**

The ornamental design for a measurement scanner for semi-conductor, as shown.

**DESCRIPTION**

FIG. 1 is a front, top and right side elevational perspective view of measurement scanner for semi-conductor showing our new design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a right elevational view thereof;  
FIG. 4 is a top plan elevational view thereof;  
FIG. 5 is a bottom plan elevational view thereof;  
FIG. 6 is a rear elevational view thereof; and,  
FIG. 7 is a left elevational view thereof.



*FIG. 1*

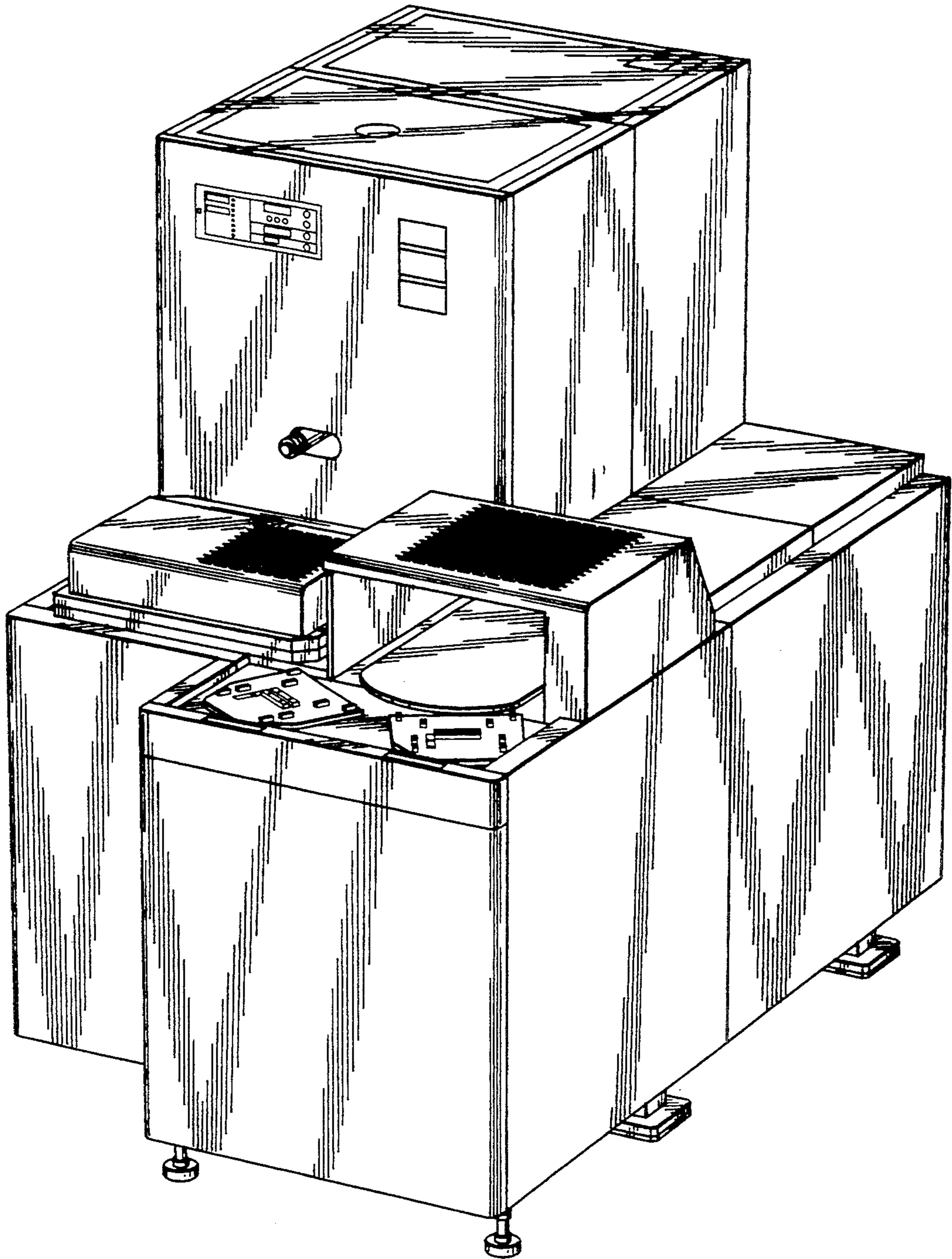


FIG. 3

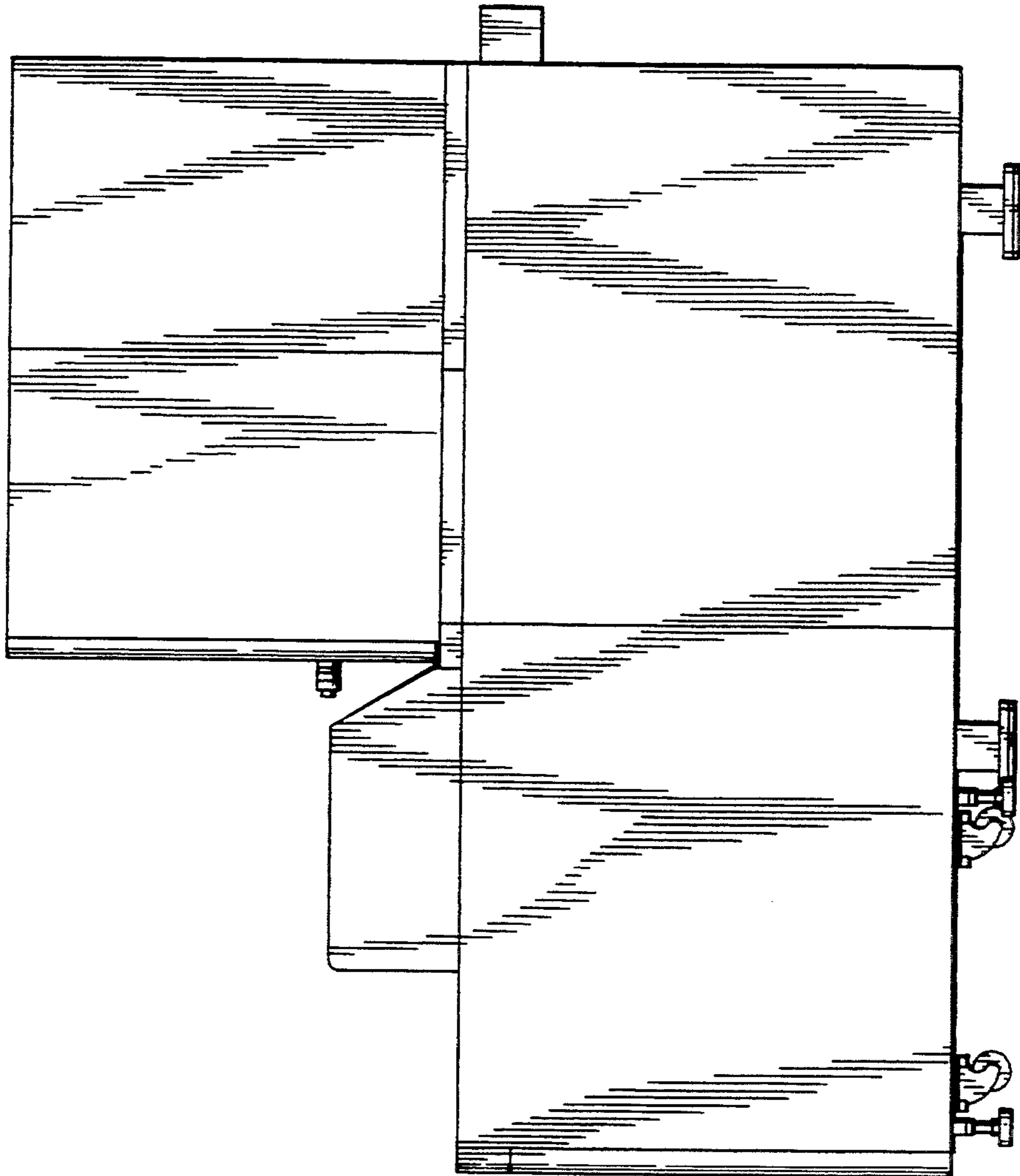


FIG. 2

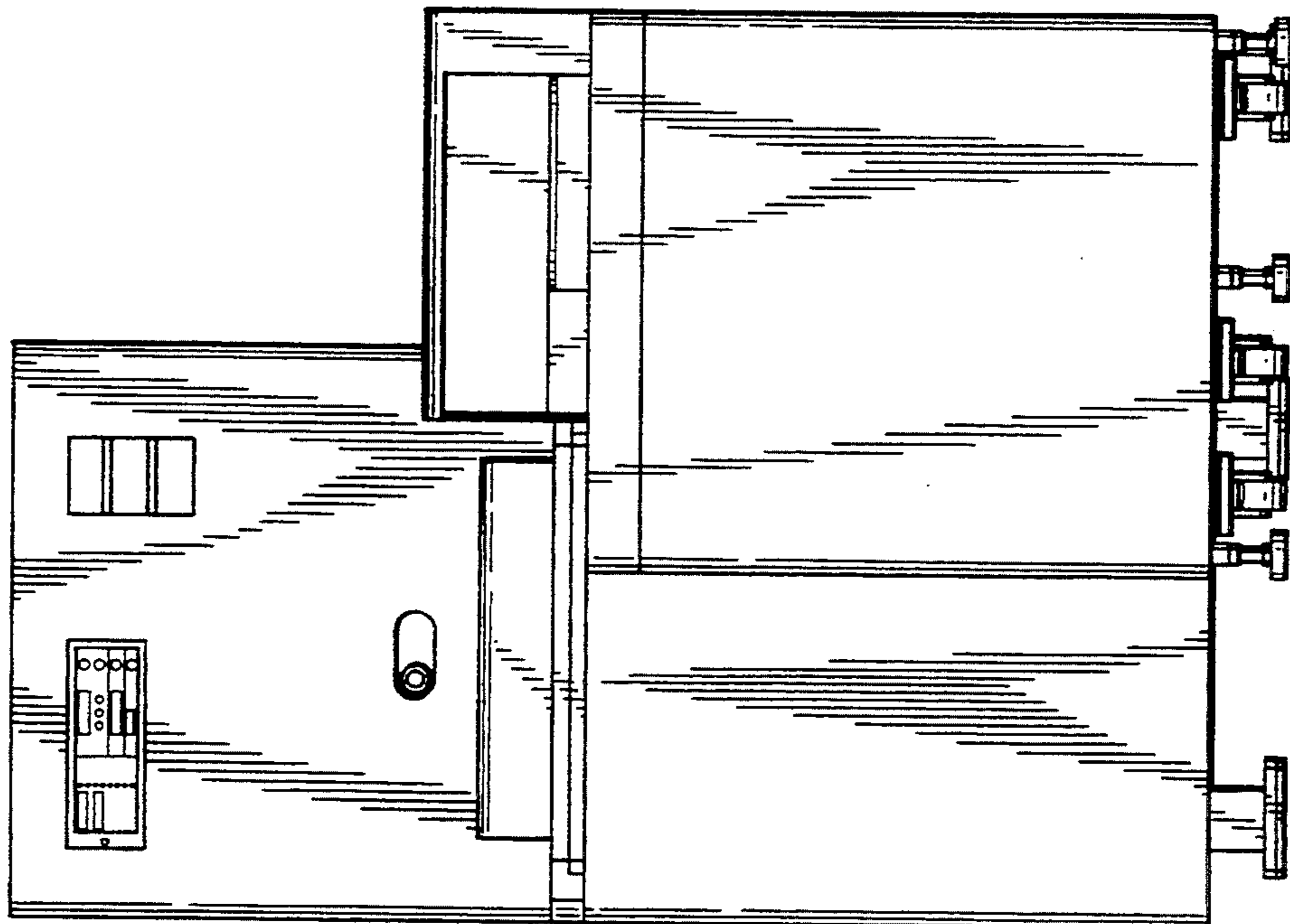




FIG. 5

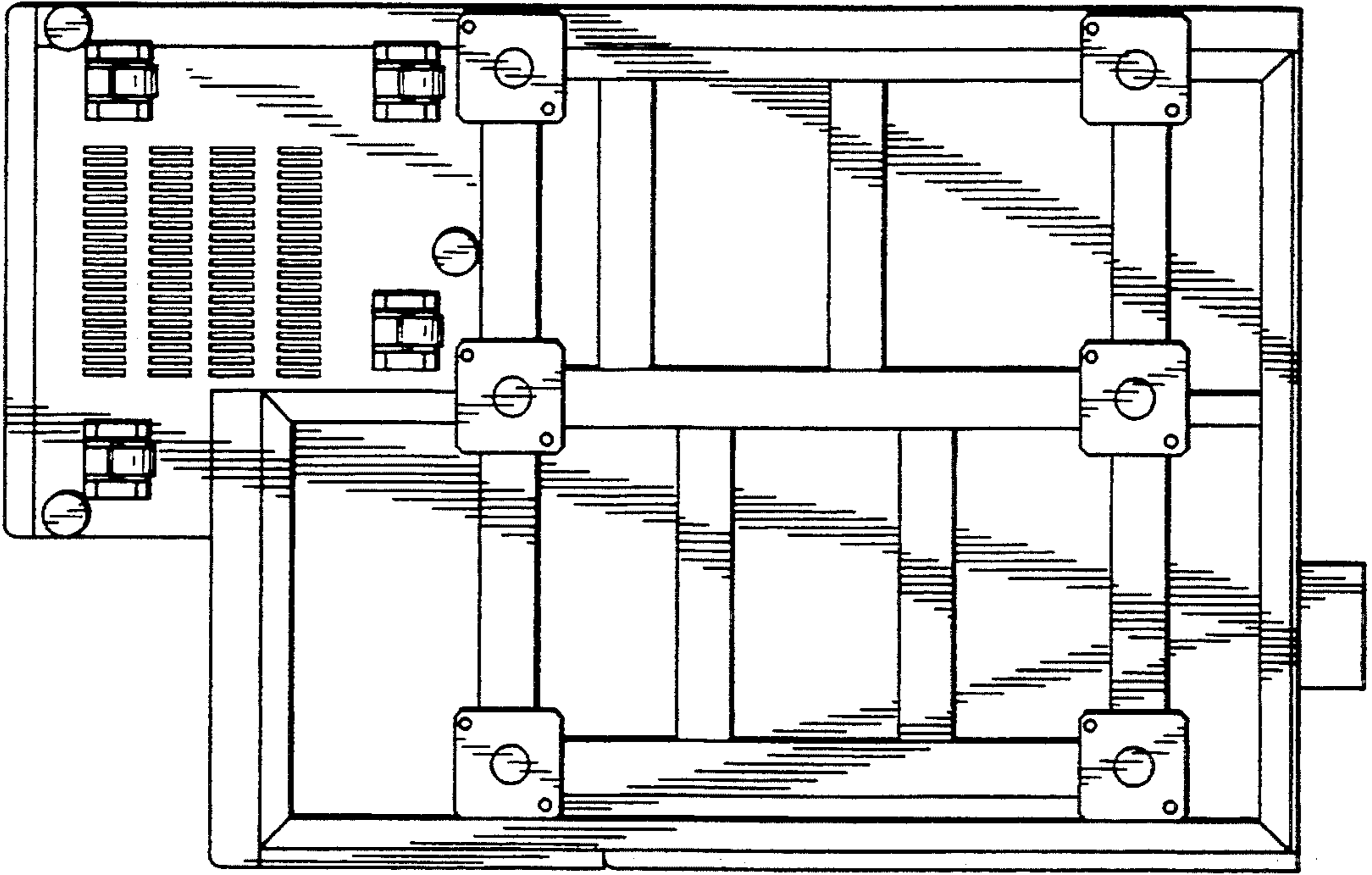


FIG. 4

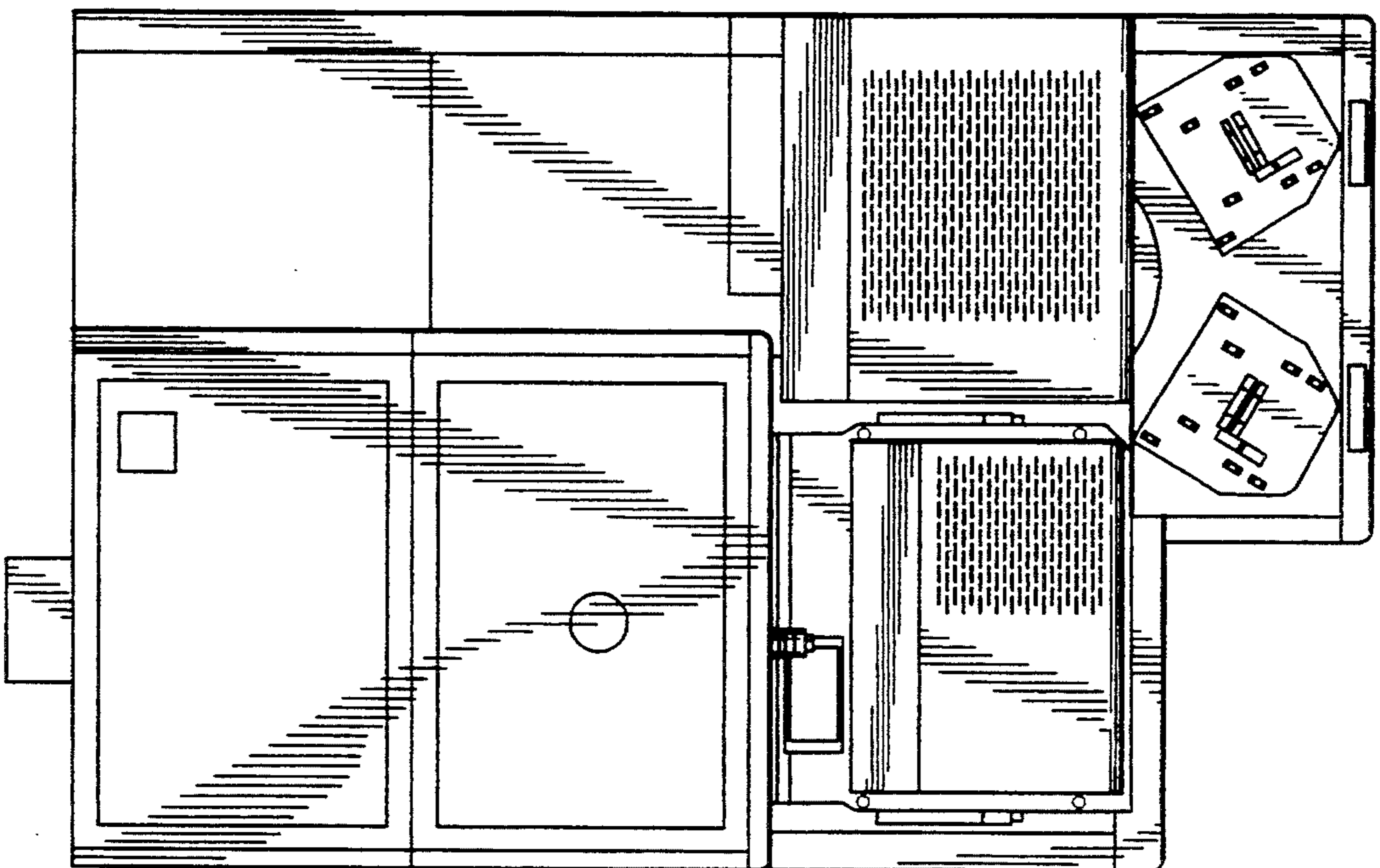


FIG. 7

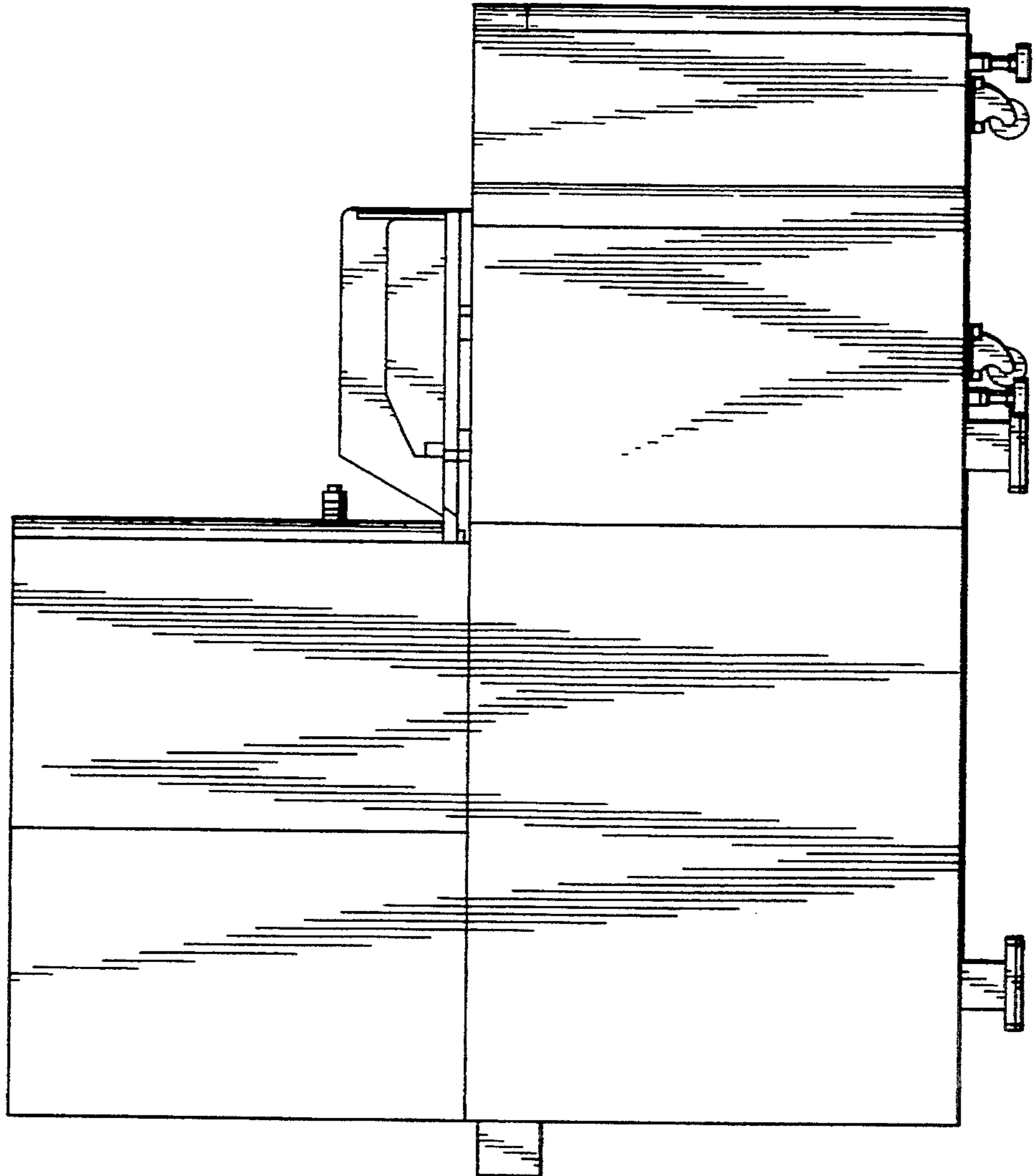


FIG. 6

